



# 1A, 30V - 60V Schottky Barrier Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Very low profile typical height of 0.68mm
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### **APPLICATIONS**

- Low voltage, high freq. inverter
- DC/DC converter
- Freewheeling diodes
- Reverse battery protection
- Car lighting

### **MECHANICAL DATA**

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	1	Α	
$V_{RRM}$	30 - 60	V	
I <sub>FSM</sub>	25	Α	
T <sub>J MAX</sub>	150	°C	
Package	Micro SMA		
Configuration	Single die		









**Micro SMA** 



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	SS13MH	SS14MH	SS16MH	UNIT
Marking code on the device		Α	В	С	
Repetitive peak reverse voltage	$V_{RRM}$	30	40	60	V
Reverse voltage, total rms value	$V_{R(RMS)}$	21	28	42	V
Forward current	I <sub>F</sub>	1		Α	
Surge peak forward current 8.3ms single half sine wave superimposed on rated load	I <sub>FSM</sub>	25		А	
Junction temperature	$T_J$	-55 to +150		°C	
Storage temperature	$T_{STG}$	-55 to +150		°C	



THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	30	°C/W
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	125	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	40	°C/W

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	SS13MH	$I_F = 0.5A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.45	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		0.52	0.55	V
	SS14MH	$I_F = 0.5A, T_J = 125$ °C		0.35	-	V
<b>F</b> (1)		$I_F = 1.0A, T_J = 125$ °C		0.46	0.50	V
Forward voltage <sup>(1)</sup>		$I_F = 0.5A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.51	-	V
	SS16MH	$I_F = 1.0A, T_J = 25$ °C		0.64	0.68	V
		$I_F = 0.5A, T_J = 125$ °C		0.46	-	V
		$I_F = 1.0A, T_J = 125$ °C		0.57	0.60	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	SS13MH SS14MH	T <sub>J</sub> = 25°C	I <sub>R</sub>	5	50	μA
		T <sub>J</sub> = 125°C		3	10	mA
		T <sub>J</sub> = 150°C		5.3	-	mA
	SS16MH	T <sub>J</sub> = 25°C	I <sub>R</sub>	5	50	μA
		T <sub>J</sub> = 125°C		3	10	mA
		T <sub>J</sub> = 150°C		6	-	mA
•	1MHz, V <sub>R</sub> = 4.0V	$C_J$	50	-	pF	
	SS16MH	, ,		40	-	pF

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
SS1xMH	Micro SMA	12,000 / Tape & Reel	

## Notes:

1. "x" defines voltage from 30V(SS13MH) to 60V(SS16MH)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

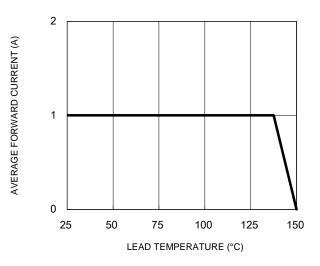


Fig.3 Typical Reverse Characteristics

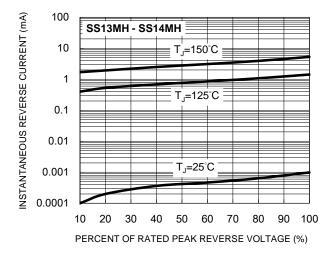


Fig.5 Typical Reverse Characteristics

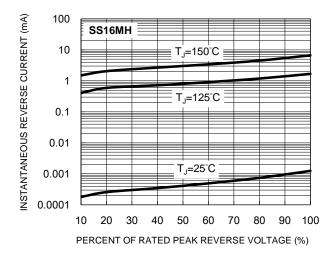
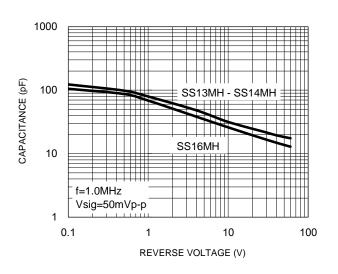


Fig.2 Typical Junction Capacitance



**Fig.4 Typical Forward Characteristics** 

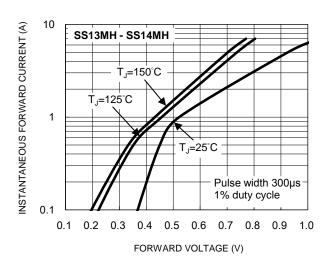
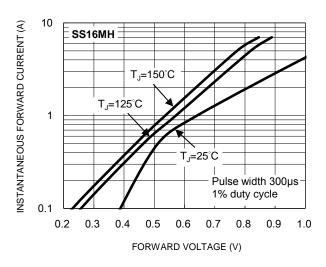


Fig.6 Typical Forward Characteristics





## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.7 Maximum Non-Repetitive Forward Surge Current

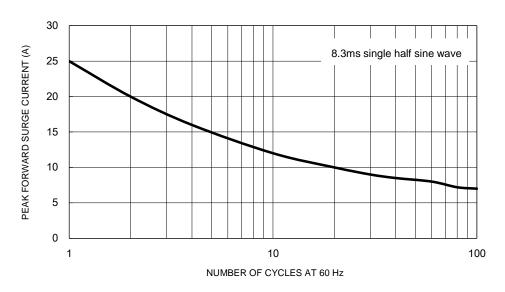
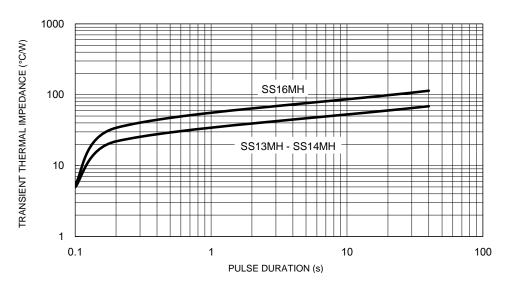


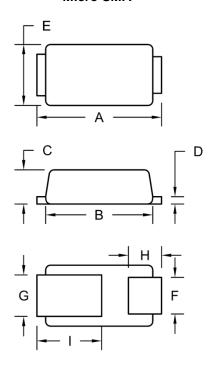
Fig.8 Typical Transient Thermal Impedance





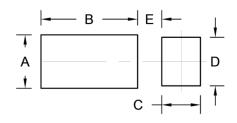
## **PACKAGE OUTLINE DIMENSIONS**

## **Micro SMA**



DIM.	Unit (mm)		Unit (	nit (inch)	
Dilvi.	Min.	Max.	Min.	Max.	
Α	2.30	2.70	0.091	0.106	
В	2.10	2.30	0.083	0.091	
С	0.63	0.73	0.025	0.029	
D	0.10	0.20	0.004	0.008	
E	1.15	1.35	0.045	0.053	
F	0.65	0.85	0.026	0.034	
G	0.75	0.95	0.030	0.037	
Н	0.55	0.75	0.022	0.030	
I	1.10	1.50	0.043	0.059	

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

## **MARKING DIAGRAM**



P/N = Marking Code ΥW = Data Code



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